

Features

1) Low on - resistance

4) 100% Rg and UIS tested

(TO220AB)

5) Halogen free

Application

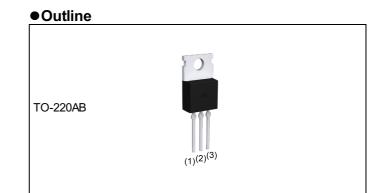
Switching

2) High power small mold package

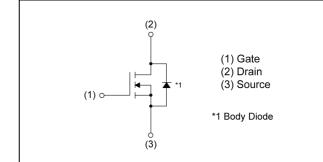
3) Pb-free lead plating ; RoHS compliant

RX1L08BGN

V _{DSS}	60V
R _{DS(on)} (Max.)	7.2mΩ
Ι _D	±80A
P _D	96W



Inner circuit



Packaging specifications

Packing	Tube
Basic ordering unit (pcs)	1000
aping code	C10
<i>N</i> arking	RX1L08BGN
	Basic ordering unit (pcs)

• Absolute maximum ratings ($T_a = 25^{\circ}C$,unless otherwise specified)

Parameter	Symbol	Value	Unit		
Drain - Source voltage		V _{DSS}	60	V	
Continuous drain current V _{GS} = 10V		۱ _D *1	±80	А	
Pulsed drain current	۱ _{DP} *2	±160	А		
Gate - Source voltage	V _{GSS}	±20	V		
Avalanche current, single pulse	I _{AS} *3	37	А		
Avalanche energy, single pulse		E _{AS} *3	52	mJ	
Power dissipation		P _D ^{*1}	96	W	
Junction temperature	T _j	150	°C		
Operating junction and storage te	mperature range	T _{stg}	-55 to +150	°C	

Thermal resistance

Peremeter	Sumbol	Values			Unit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *1	-	-	1.3	°C/W

•Electrical characteristics (T_a = 25°C)

Deremeter	Current el	Conditions	Values			Lincit	
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		60	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}} I_{D} = 1 mA$ referenced to 25°C		-	60	-	mV/°C	
Zero gate voltage drain current	I_{DSS} V_{DS} = 60V, V_{GS} = 0V		-	-	10	μA	
Gate - Source leakage current	I_{GSS} $V_{GS} = \pm 20V, V_{DS} = 0V$		-	-	±500	nA	
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 50 \mu A$	1.0	-	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$			-5.6	-	mV/°C	
Static drain - source	D *4	V _{GS} = 10V, I _D = 80A	-	5.2	7.2		
on - state resistance	R _{DS(on)} *4	V _{GS} = 4.5V, I _D = 40A	-	7.3	10.9	mΩ	
Gate resistance	R_G f = 1MHz, open drain		-	1.8	-	Ω	
Forward Transfer Admittance	$ Y_{fs} ^{*4}$ $V_{DS} = 5V, I_D = 40A$		24	-	-	S	

*1 T_c=25°C, Limited only by maximum temperature allowed.

*2 Pw \leq 10µs , Duty cycle \leq 1%

*3 L \simeq 0.05mH, V_{DD} = 30V, R_G = 25 Ω , Starting T_j = 25°C Fig.3-1,3-2

*4 Pulsed



•Electrical characteristics (T_a = 25°C)

Deremeter	Cumphed	Conditions		Unit		
Parameter	Symbol	I Conditions		Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	2600	-	
Output capacitance	C _{oss}	V _{DS} = 30V	-	510	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	130	-	
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 30V, V_{GS}$ = 10V	-	17	-	
Rise time	tr ^{*4}	I _D = 40A	-	32	-	
Turn - off delay time	t _{d(off)} *4	$R_L \simeq 0.75\Omega$	-	71	-	ns
Fall time	t _f *4	R _G = 10Ω	-	34	-	

• Gate charge characteristics ($T_a = 25^{\circ}C$)

Deremeter	Sumbol	Symbol Conditions		Values			Linit		
Parameter	Зупрог			Min.	Тур.	Max.	Unit		
Tatal acta charge	O *4	V _{GS}	V _{GS} = 10V	-	55	-			
Total gate charge	Q _g *4	Q _g	Qg	$V_{DD} \simeq 30V$		-	27	-	nC
Gate - Source charge	Q _{gs} *4	I _D = 40A	V _{GS} = 4.5V	-	11	-	nc		
Gate - Drain charge	Q _{gd} *4			-	9.8	-			

•Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Deremeter	Sumbol	Conditiono		Unit		
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit
Continuous forward current	I _S	T _a = 25°C	-	-	80	А
Pulse forward current	I _{SP} *2	$T_{a} = 25 C$	-	-	160	А
Forward voltage	V _{SD} *4	V _{GS} = 0V, I _S = 80A	-	-	1.2	V
Reverse recovery time	t _{rr} *4	I _S = 50A, V _{GS} =0V	-	42	-	ns
Reverse recovery charge	Q _{rr} *4	di/dt = 100A/µs	-	53	-	nC



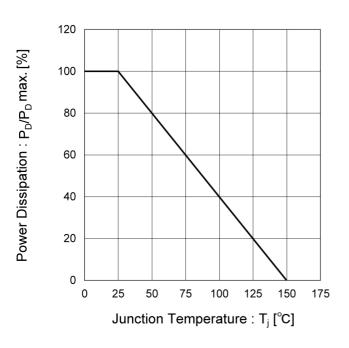


Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

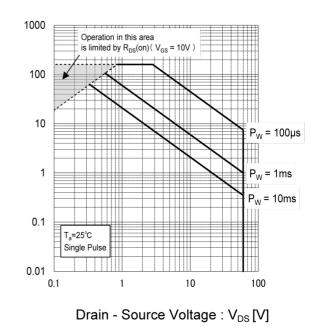
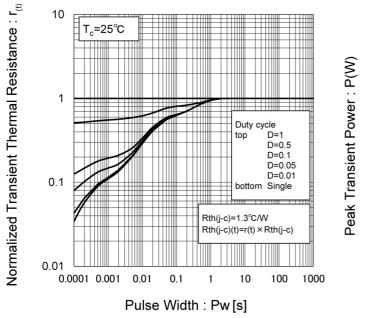


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

Fig.4 Single Pulse Maximum Power dissipation





Drain Current : I_D [A]



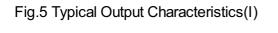
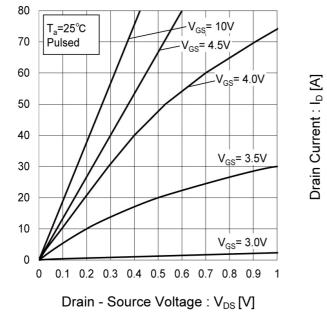


Fig.6 Typical Output Characteristics(II)



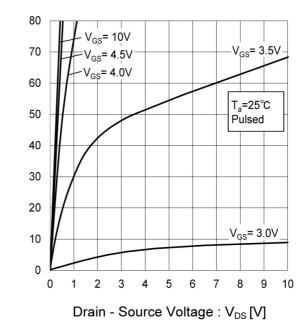
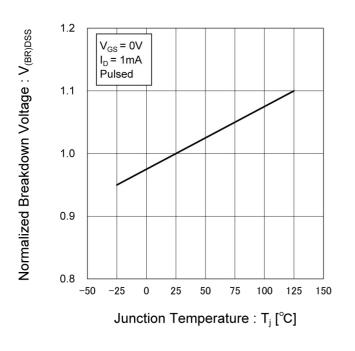


Fig.7 Breakdown Voltage vs. Junction Temperature





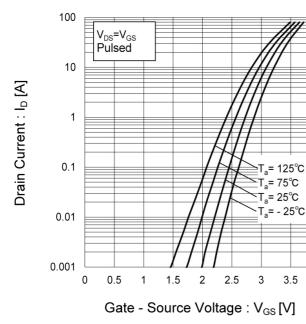


Fig.8 Typical Transfer Characteristics

Fig.9 Gate Threshold Voltage vs. Junction Temperature

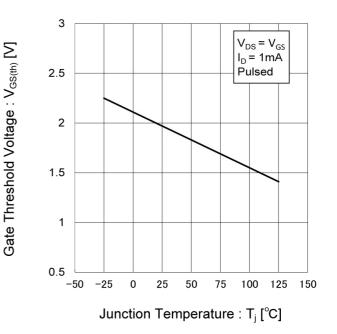
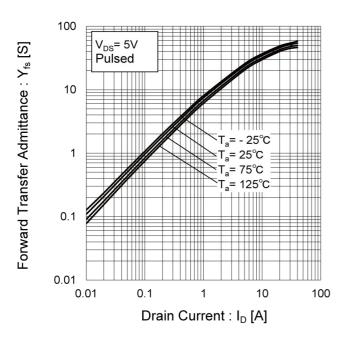


Fig.10 Forward Transfer Admittance vs. Drain Current

4



6/11



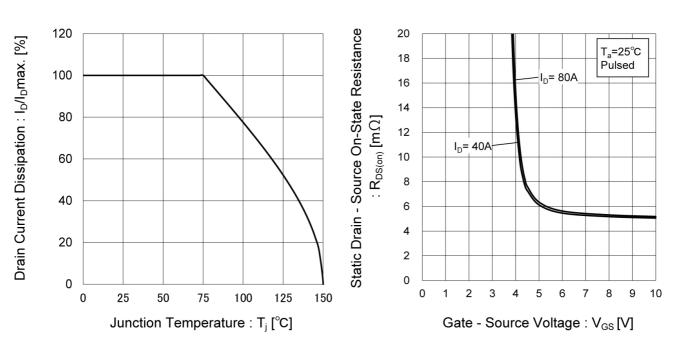
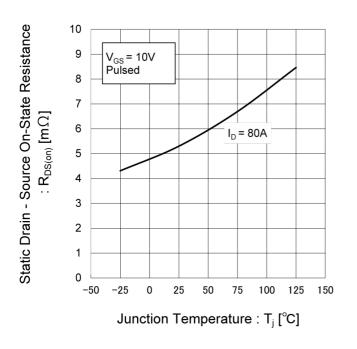


Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature





7/11



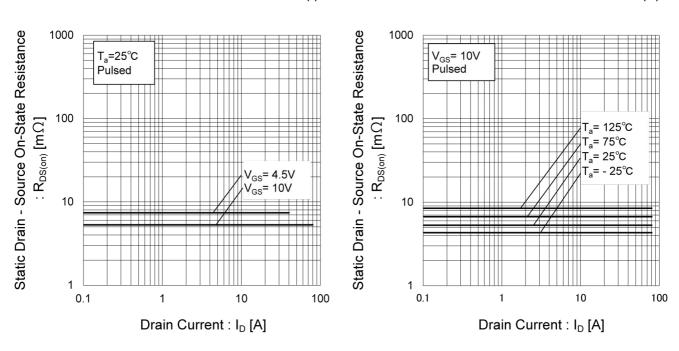
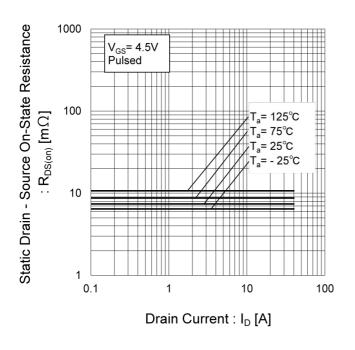


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I) Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)





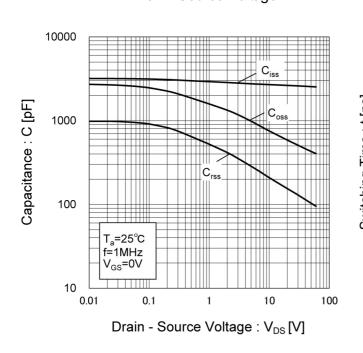


Fig.17 Typical Capacitance vs. Drain - Source Voltage

Fig.18 Switching Characteristics

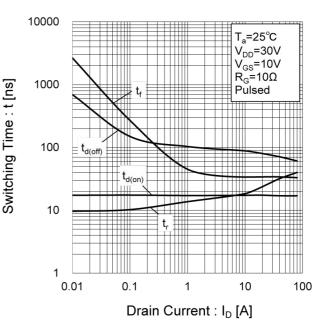


Fig.19 Dynamic Input Characteristics

Gate - Source Voltage : V_{GS} [V]

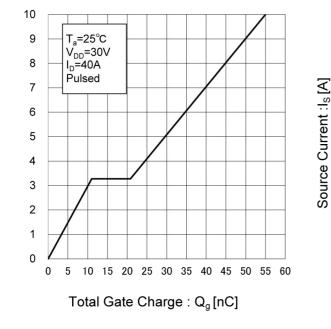
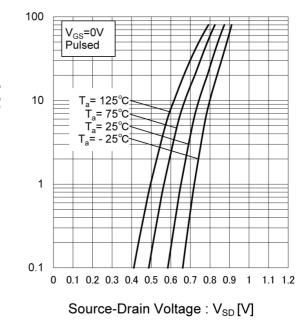


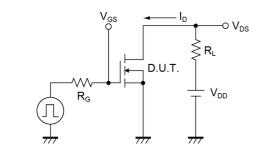
Fig.20 Source Current vs. Source Drain Voltage





Measurement circuits







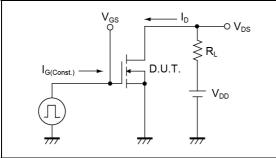


Fig.3-1 Avalanche Measurement Circuit

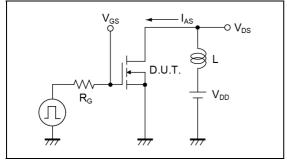


Fig.1-2 Switching Waveforms

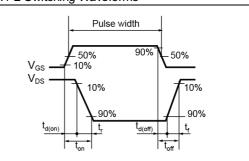


Fig.2-2 Gate Charge Waveform

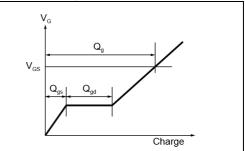
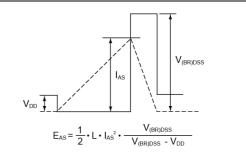
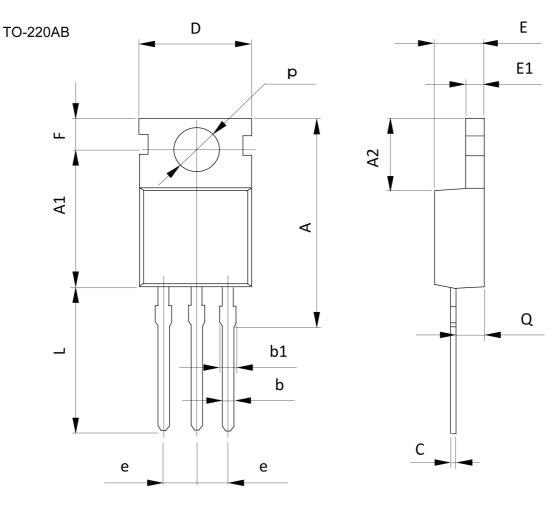


Fig.3-2 Avalanche Waveform





Dimensions



	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
А	18.3	18.95	0.720	0.746
A1	12.7	13.1	0.500	0.516
A2	6.3	6.7	0.248	0.264
b	0.6	1	0.024	0.039
b1	1.07	1.47	0.042	0.058
с	0.4	0.7	0.016	0.028
D	9.7	10.1	0.382	0.398
E	4.3	4.7	0.169	0.185
е	2.5	54	0.1	00
E1	1.1	1.5	0.043	0.059
F	2.6	3.2	0.102	0.126
L	9.88	10.28	0.389	0.405
р	3.4	3.8	0.134	0.150
Q	2.2	2.6	0.087	0.102

Dimension in mm/inches



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(Note1) Medical Equipment Classification of the Specific Applications

JÁPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSII
CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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